Final Product Change Notification

201707023F01

Issue Date: 23-Aug-2017
Effective Date: 20-Nov-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

Change Category

[ ] Wafer Fab Process	[X] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage

Laser Groove Implementation with Single Cut Blade Saw Process For SPC5777M TePBGA Package

Details of this Change

NXP Semiconductors announces the implementation of laser groove with single cut blade saw process for SPC5777M with package type TePBGA.

The use of laser groove in NXP Semiconductors is being expanded from existing product technologies with the same wafer thickness that have run since 2008 to also include C55 products.

The laser groove process with single cut blade saw in the die singulation process for SPC5777M with package type TePBGA is being introduced on product assembled at NXP Kuala Lumpur, Malaysia (NXP-ATKL) assembly site.

The use of laser groove with single cut blade saw process improves the current singulation process which is performed using step cut blade saw.

A visual comparison between the die singulation methods is provided in the supplemental material attached with this notification.

This change corresponds to the ZVEI Delta Qualification Matrix ID: SEM-PA-19.

Why do we Implement this Change

The implementation of laser groove with single cut blade saw process will reduce the amount of singulation defects to a lower ppm level. This is validated through internal inspection data that is attached with this notification.

Historical data from products produced with the same wafer thickness as the SPC5777M that have implemented the laser groove process since year 2008 recorded zero customer returns due to die singulation issues.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from 11-Sep-2017
Date above reflects qualified sample part number availability.

Sample part numbers:
KPC5777MK0MVA8 - 512 TePBGA
KPC5777MK0MVA8R - 512 TePBGA
KPC5777MK0MVU8 - 416 TePBGA
KPC5777MK0MVU8R - 416 TePBGA

Production

Planned first shipment 15-Nov-2017

Impact

no impact to the product's functionality anticipated.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 22-Sep-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Name	Status	Product Line
SPC5777MK0MVU8	935320541557	SPC5777MK0MVU8	QUAD CORE 8M FLASH	BGA416	RFS	BL Auto Micro Processors
SPC5777MK0MVA8	935315463557	SPC5777MK0MVA8	QUAD CORE 8M FLASH 404K	FBGA512	RFS	BL Auto Micro Processors